



## Composite Structures - Modelling, Testing and Manufacturing

Guest Editors:

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Deadline for manuscript  
submissions:

**closed (31 October 2023)**

### Message from the Guest Editors

Dear Colleagues,

In this Special Issue on “Composite Structures - Modelling, Testing and Manufacturing”, we welcome review articles and original research papers, fundamental or applied, theoretical, numerical, or experimental, on composite structures. Topics include, but are not limited to:

- Composite materials and components, lightweight structures
- Design and manufacturing of lightweight hybrid structures
- Engineering methods of design, calculations, and simulations
- Rheology of composite materials and structures
- Composite from renewable materials and recycling of composite structures
- Processing and technology of composite materials and lightweight structures
- Non-destructive investigation methods for composite materials and structures
- Functional and special composite materials (e.g., smart materials)

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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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